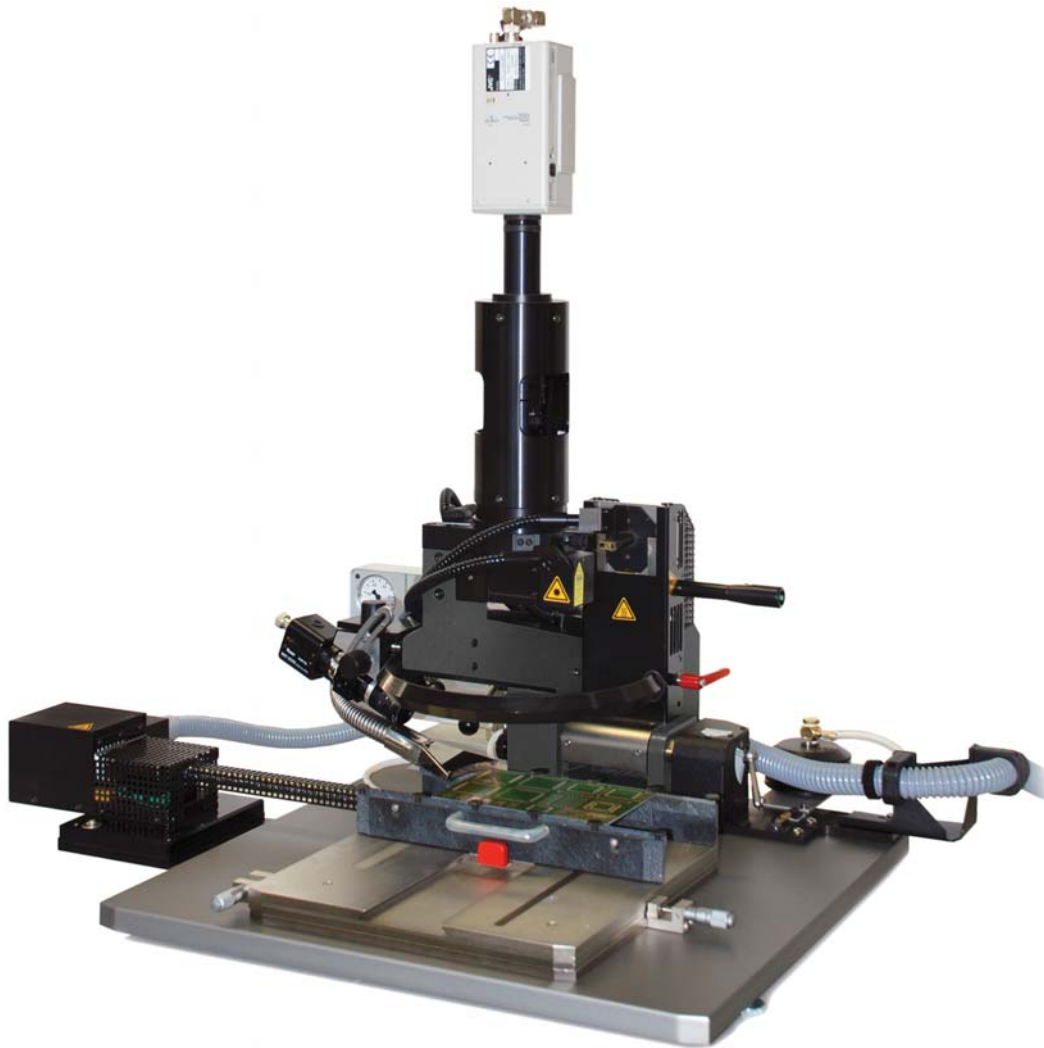


## FINEPLACER<sup>®</sup> micro rs

Hot Air SMD Rework Station



advanced rework

FINEPLACER<sup>®</sup> micro rs

The **FINEPLACER<sup>®</sup> micro rs** is an enhanced hot air rework station for assembly and rework of all standard types of SMD components.

A high level of process modularity allows all rework process steps within one system. The **FINEPLACER<sup>®</sup> micro rs** system is at home in production environments, R&D, process development and prototyping.

Application area from ultra small to large SMD components on small to large sized PCBs, with the goal to have highly reproducible soldering results.

### Highlights

- Industry-leading thermal management
- Placement accuracy better than 10  $\mu$ m
- Component sizes from 0.125<sup>2</sup> mm<sup>2</sup> to 90<sup>2</sup> mm<sup>2</sup>\*
- Board sizes up to 460 mm x 310 mm\*
- High efficiency board heater
- Closed loop force control\*
- Automated top heater calibration

\* depending on configuration

## Features

- Automated soldering processes
- Overlay vision alignment system (VAS) with fixed beam splitter
- Modular design
- Integrated Process Management (IPM)
- Real time process observation camera
- Adaptive process library
- Process transfer from system to system

## Benefits

- Hands-off component placement, user independent process operation\*
- Outstanding placement accuracy and instant operation without adjustments
- Provides high level of application flexibility
- Synchronized control of all process related parameters: force, temperature, time, flow, power, process environment, light and vision
- Immediate visual feedback reduces process development time
- Fast and easy process development
- Identical results on different machines allow central profile development, administration and distribution

## Technologies

- Component removal
- Site cleaning
- Re-balling (single, array)
- Solder paste printing (component, PCB)
- Dispensing
- Dipping
- Soldering
- Desoldering

## Applications

- Soldering of:
  - BGA,  $\mu$ BGA/CSP, QFN, PoP, QFP, PGA,
  - Small passives down to 0201
  - RF shields, RF frames
  - Connectors, sockets
  - Sub assemblies, daughter boards
  - Flipchip (C4)
- Through hole rework (THR)
- Pin in paste (PiP)
- Reworkable underfill, conformal coating
- Single ball rework

## Technical Specifications

Placement accuracy:	10 $\mu$ m
Field of view (min) <sup>1</sup> :	13.8 mm x 11.6 mm
Field of view (max) <sup>1</sup> :	71 mm x 58 mm
Component size (min) <sup>1</sup> :	0.125 mm x 0.125 mm
Component size (max) <sup>1</sup> :	60 mm x 60 mm
<b>Power (reflow module):</b>	900 W
Temperature ramp rate:	1 K/s - 50 K/s
Flow range:	10 NI/min - 70 NI/min
<b>Power (board heater):</b>	2100 W
Heated area (max):	380 mm x 285 mm
Thermocouples*:	2 - 8

\* depending on configuration

<sup>1</sup> standard value, other values on request

## Modules

Reflow module  
 Board heater  
 Board temperature sensor (IR)  
 Process gas module  
 Solder removal module  
 BGA reballing module  
 Board printing tools  
 Component printing module (DCP)  
 Flux transfer station  
 Lighting options  
 Process video module

## Notes:

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